METHODS FOR ASSEMBLY AND PACKAGING OF FLIP CHIP CONFIGURED DICE WITH INTERPOSER

ABSTRACT

A method and for assembly one or more flip chip configured semiconductor dice with an interposer substrate to form a flip chip semiconductor device assembly. The flip chip semiconductor device assembly includes a conductively bumped semiconductor die and an interposer substrate having plurality of recesses formed therein. The semiconductor die is mounted to the interposer substrate with the conductive bumps disposed in the plurality of recesses so that the die face is adjacent the facing surface of the interposer substrate. One or more openings may be provided in an opposing surface of the interposer substrate which extend to the plurality of recesses and the conductive bumps disposed therein. Dielectric filler material may then be introduced through the one or more openings to the recesses and, optionally, between the semiconductor die and interposer substrate.

[Figure 6B]



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